Device Material Content

5555 NE Moore Ct.
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Package: 16 PDIP with SnPb Plating
Total Device Weight 1.01 Grams

April, 2004	% of Total Pkg. Wt.	Weight (g)	% of Total Pkg. Wt.	Weight (g)	Substance	CAS #	Notes / Assumptions:
Die	2.77%	0.029			Silicon	7440-21-3	Die size: 4.0 x 6.0 mm.
Mold	66.87%	0.675					Mold Compound Density varies between 1.7 and 2.3 grams/cc
			46.61%	0.471	Silica	60676-86-0	60 to 90% Silica Fused (LSC uses 69.7% in our calculation)
			16.72%	0.169	Epoxy Resin	129915-35-1	15 to 40% Epoxy Resin (LSC uses 25% in our calculation).
			2.01%	0.020	Antimony Trioxide	1309-64-4	o) NOTE: Total includes Phenol and Epoxy resins (exact % is Trade secret)
			1.34%	0.014	Brominated Epoxy resin	68928-70-1	1% to 5% Antimony Trioxide (LSC uses 3% in our calculation)
			0.20%	0.002	Carbon black	1333-86-4	1 to 3% Brominated Epoxy Resin (LSC uses 2% in our calculation).
							0.1 to 0.5% Carbon black (LSC uses 0.3% in our calculation)
D/A Epoxy	0.24%	0.002			Silver-filled Epoxy		
			0.19%	0.002	Silver (Ag)	7440-22-4	Die attach epoxy Density: 4 grams/cc
			0.05%	0.0005	other	-	(silver content: 60-100%; LSC uses 80% in our calculation)
Wire	0.07%	0.001			Gold (Au)	7440-57-5	1.2 mil wire diameter; 1 wire for each package lead; wire length 3 mm
Lead Plating	2.34%	0.024					
			1.99%	0.020	Tin (Sn)	7440-31-5	Nominal: 85% Sn, 15% Pb
			0.35%	0.004	Lead (Pb)	7439-92-1	Thickness is 0.015mm
Leadframe	27.71%	0.280					Leadframe composition (C194):
			27.01%	0.273	Copper (Cu)	7440-50-8	97.46% Cu
			0.65%	0.007	Iron (Fe)	7439-89-6	2.35% Fe
			0.03%	0.0003	Zinc (Zn)	7440-66-6	0.12% Zn
			0.02%	0.0002	Phosphorus (P)	7723-14-0	0.07% P
							Leadframe thickness is nominal (per Case Outline).

Notes:
The values listed above are nominal values based on studies of representatives of this particular package type, and are believed to be as accurate as possible.

The information provided above is representative of the package as of the date listed, and is subject to change at any time.
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